SMD ▪ B
19-237/R6GHBHC-A04/2T

Features
. Package in 8mm tape on 7″ diameter reel.
. Compatible with automatic placement equipment.
. Compatible with infrared and vapor phase reflow solder process.
. Multi-color type.
. Pb-free.
. The product itself will remain within RoHS compliant version.

Description
. The 19-237 SMD LED is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
. Besides, lightweight makes them ideal for miniature applications. etc.

Applications
. Backlighting in dashboard and switch.
. Telecommunication: indicator and backlighting in telephone and fax.
. Flat backlight for LCD, switch and symbol.
. General use.

Device Selection Guide

Code	Chip Materials	Emitted Color	Resin Color
R6	AlGaInP	Brilliant Red	
GH	InGaN	Brilliant Green	Water Clear
BH	InGaN	Blue	

www.everlight.com

Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Code	Rating	Unit
Reverse Voltage	V_R		5	V
Forward Current	I_F		25	mA
Peak Forward Current (Duty 1/10 @1KHz)	I_{FP}	R6	60	mA
		GH	100	
		BH	100	
Power Dissipation	Pd	R6	60	mW
		GH	95	
		BH	95	
Electrostatic Discharge(HBM)	ESD	R6	2000	V
		GH	150	
		BH	150	
Operating Temperature	T_{opr}		-40 ~ +85	℃
Storage Temperature	Tstg		-40 ~ +90	℃
Soldering Temperature	Tsol		Reflow Soldering : 260 ℃ for 10 sec. Hand Soldering : 350 ℃ for 3 sec.	

www.everlight.com

Electro-Optical Characteristics (Ta=25℃)

Parameter	Symbol	Code	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I_V	R6	18.0	-----	57.0	mcd	
		GH	28.5		112		
		BH	11.5		28.5		
Viewing Angle	$2\theta_{1/2}$		-----	120	-----	Deg	
Peak Wavelength	λp	R6	-----	632	-----	nm	
		GH	-----	518	-----		
		BH	-----	468	-----		
Dominant Wavelength	λd	R6	613	-----	627	nm	I_F=5mA
		GH	520	-----	530		
		BH	465	-----	475		
Spectrum Radiation Bandwidth	$\triangle \lambda$	R6	-----	20	-----	nm	
		GH	-----	35	-----		
		BH	-----	25	-----		
Forward Voltage	V_F	R6	1.7	-----	2.2	V	
		GH	2.6	-----	3.0		
		BH	2.6	-----	3.0		
Reverse Current	I_R	R6			10	µA	V_R=5V
		GH			50		
		BH	-----	-----	50		

Note:
1. Tolerance of Luminous Intensity: ±11%
2. Tolerance of Dominant Wavelength: ±1nm
3. Tolerance of Forward Voltage: ±0.1V

www.everlight.com

R6
Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
M	18.0	28.5		
N	28.5	45.0	mcd	I$_F$=5mA
P	45.0	57.0		

GH
Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
N	28.5	45.0		
P	45.0	72.0	mcd	I$_F$=5mA
Q	72.0	112		

Bin Range Of Forward Voltage

Bin Code	Min.	Max.	Unit	Condition
1	2.6	2.8		
2	2.8	3.0	V	I$_F$=5mA

BH
Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
L	11.5	18.0		
M	18.0	28.5	mcd	I$_F$=5mA

Bin Range Of Forward Voltage

Bin Code	Min.	Max.	Unit	Condition
1	2.6	2.8		
2	2.8	3.0	V	I$_F$=5mA

Note:
1. Tolerance of Luminous Intensity: ±11%
2. Tolerance of Forward Voltage: ±0.1V

www.everlight.com
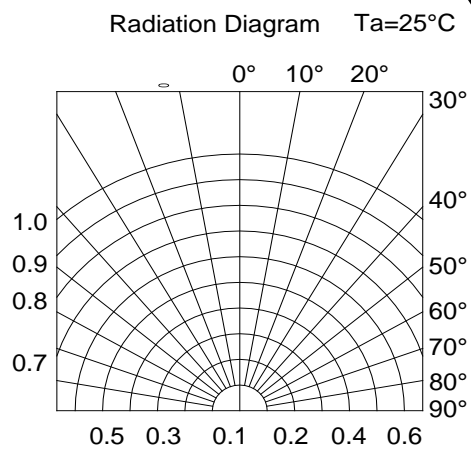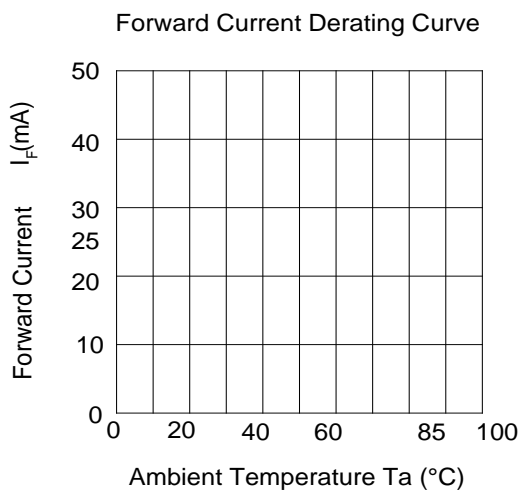
Typical Electro-Optical Characteristics Curves

R6

Spectrum Distribution

Ta=25°C

Forward Current vs.
Forward Voltage

Ta=25°C

Luminous Intensity vs.
Ambient Temperature
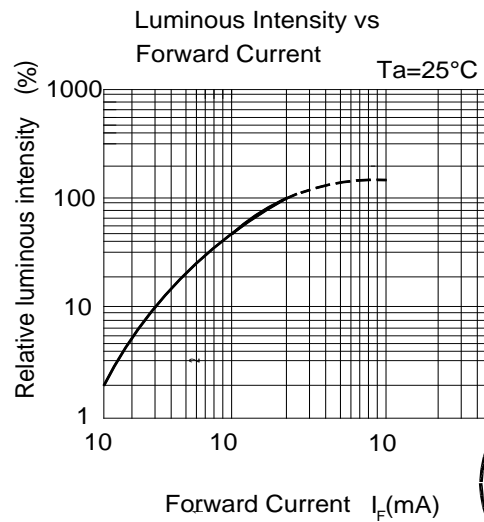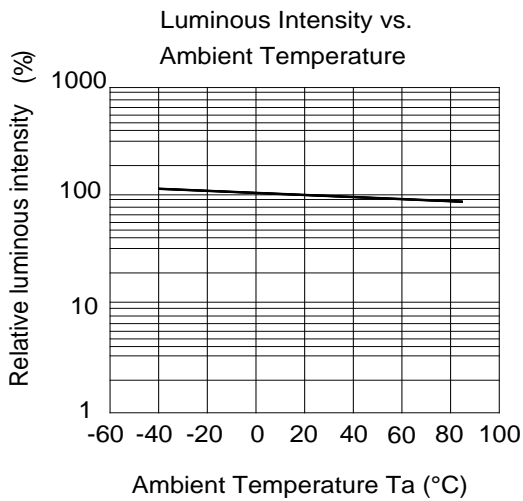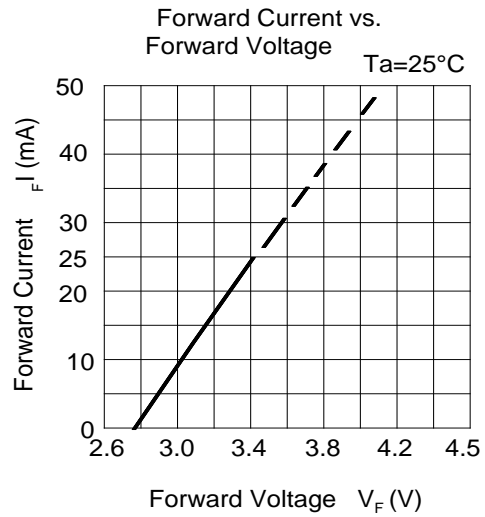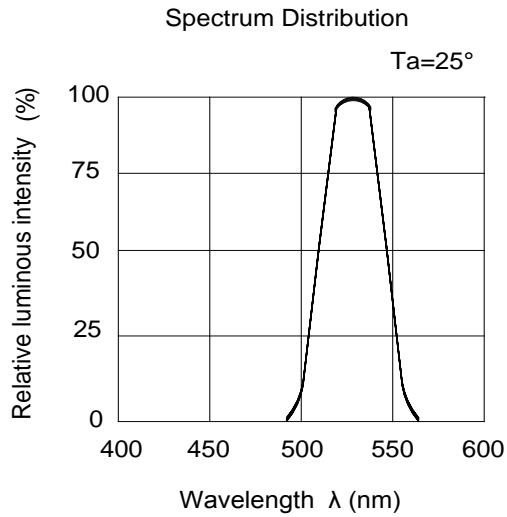
Luminous Intensity vs.
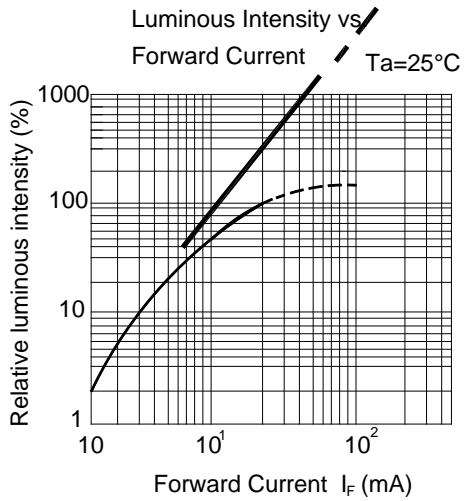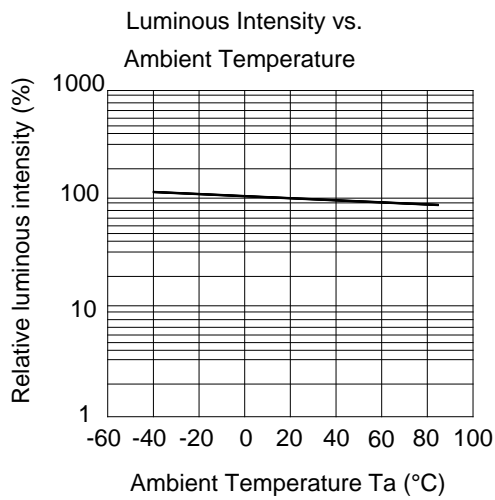Forward Current

Ta=25°C

Forward Current Derating Curve
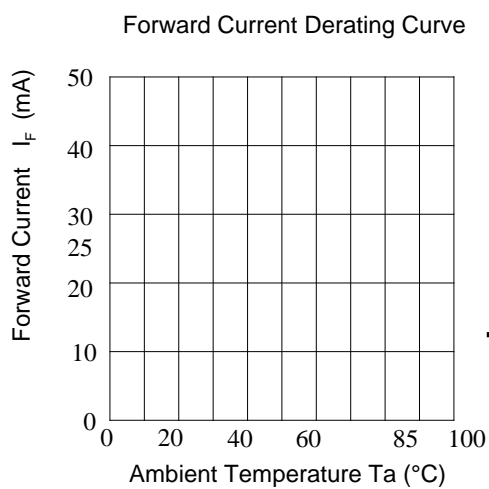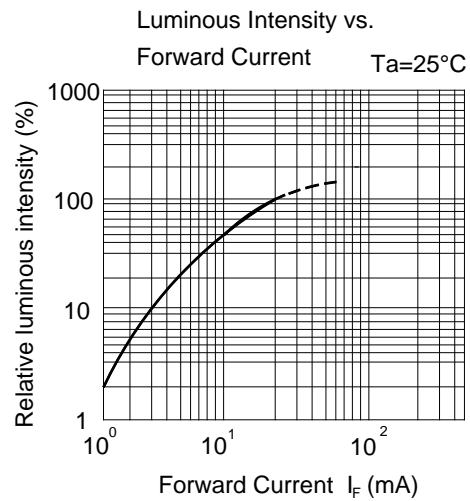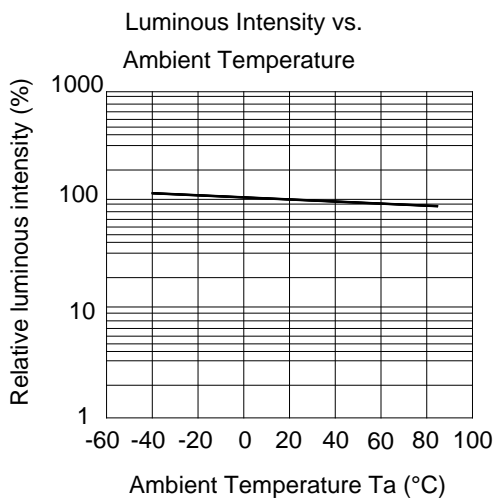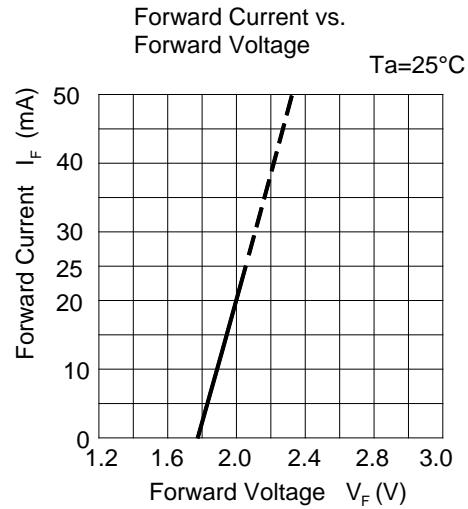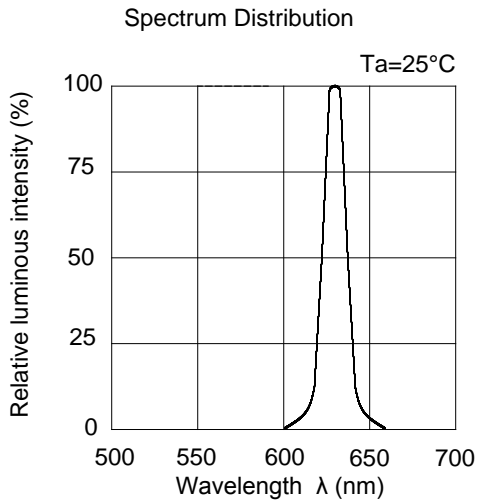
Radiation Diagram   Ta=25°C

Typical Electro-Optical Characteristics Curves

GH

Spectrum Distribution

Ta=25°

Relative luminous intensity (%) vs Wavelength λ (nm)

Forward Current vs. Forward Voltage

Ta=25°C

Forward Current I_F (mA) vs Forward Voltage V_F (V)

Luminous Intensity vs. Ambient Temperature

Relative luminous intensity (%) vs Ambient Temperature Ta (°C)

Luminous Intensity vs Forward Current

Ta=25°C

Relative luminous intensity (%) vs Forward Current I_F (mA)

Forward Current Derating Curve

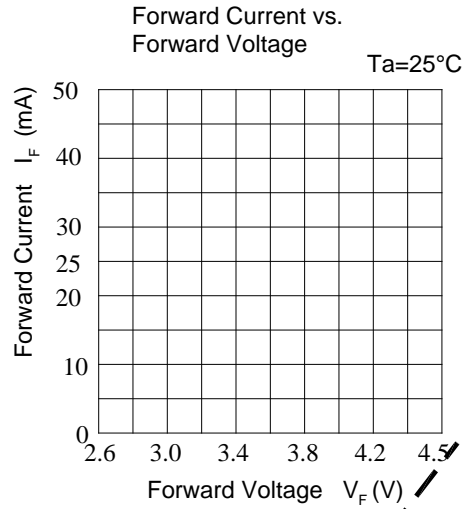Forward Current I_F (mA) vs Ambient Temperature Ta (°C)
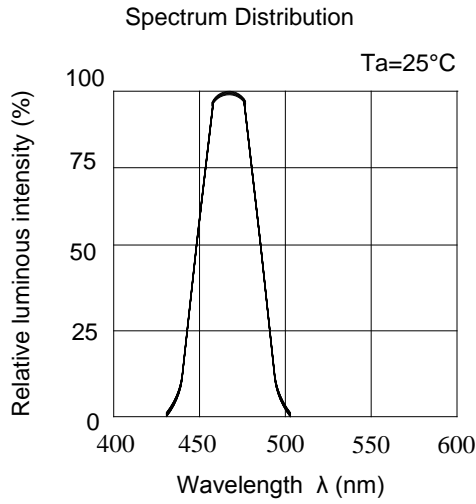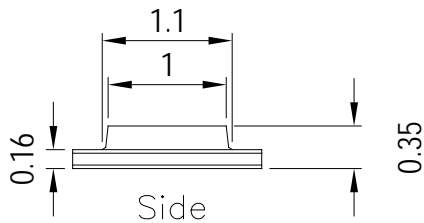
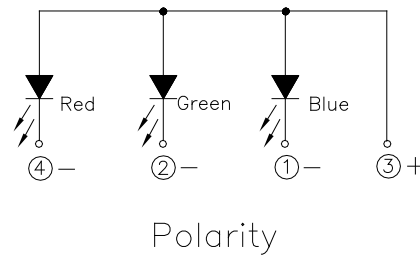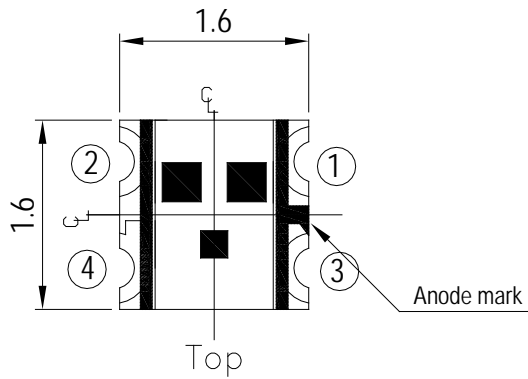Radiation Diagram   Ta=25°C

EVERLIGHT

Typical Electro-Optical Characteristics Curves

BH

Spectrum Distribution

Ta=25°C

Forward Current vs.
Forward Voltage

Ta=25°C

Luminous Intensity vs.
Ambient Temperature

Luminous Intensity vs.
Forward Current   Ta=25°C

Forward Current Derating Curve

Radiation Diagram   Ta=25°C

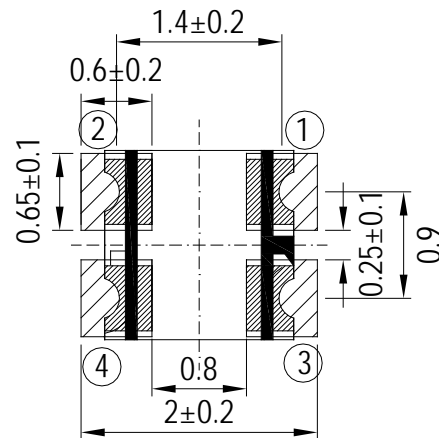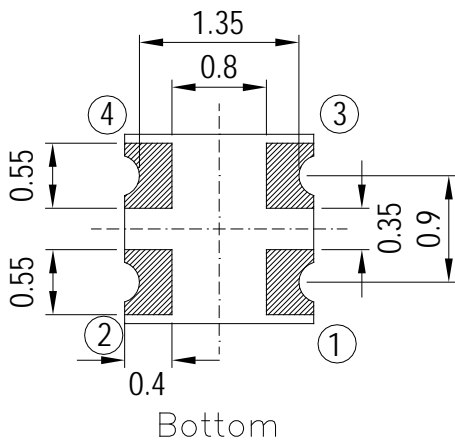www.everlight.com

EVERLIGHT

Package Dimension

Top

Polarity

Side

Recommend soldering pad

Bottom

Suggested pad dimension is just for reference only.
Please modify the pad dimension based on individual need.
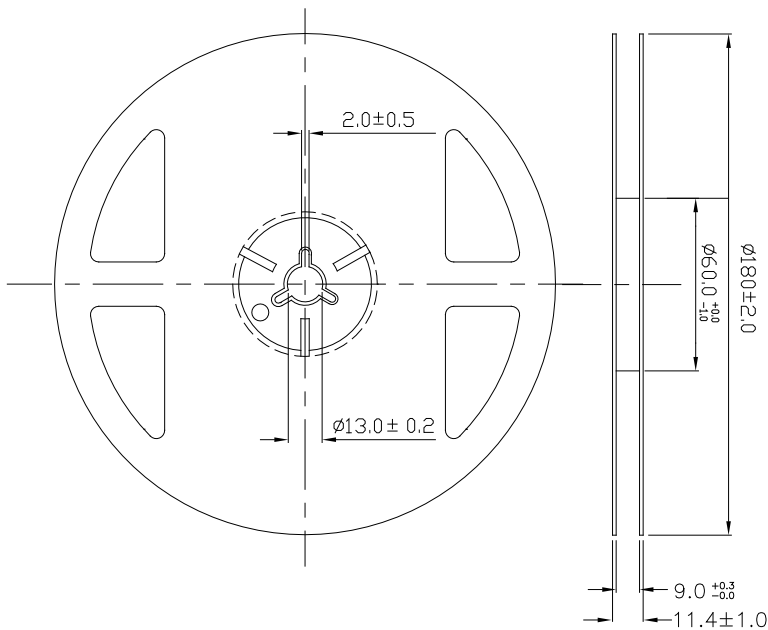
Note: Tolerances unless mentioned ±0.1mm. Unit = mm

www.everlight.com

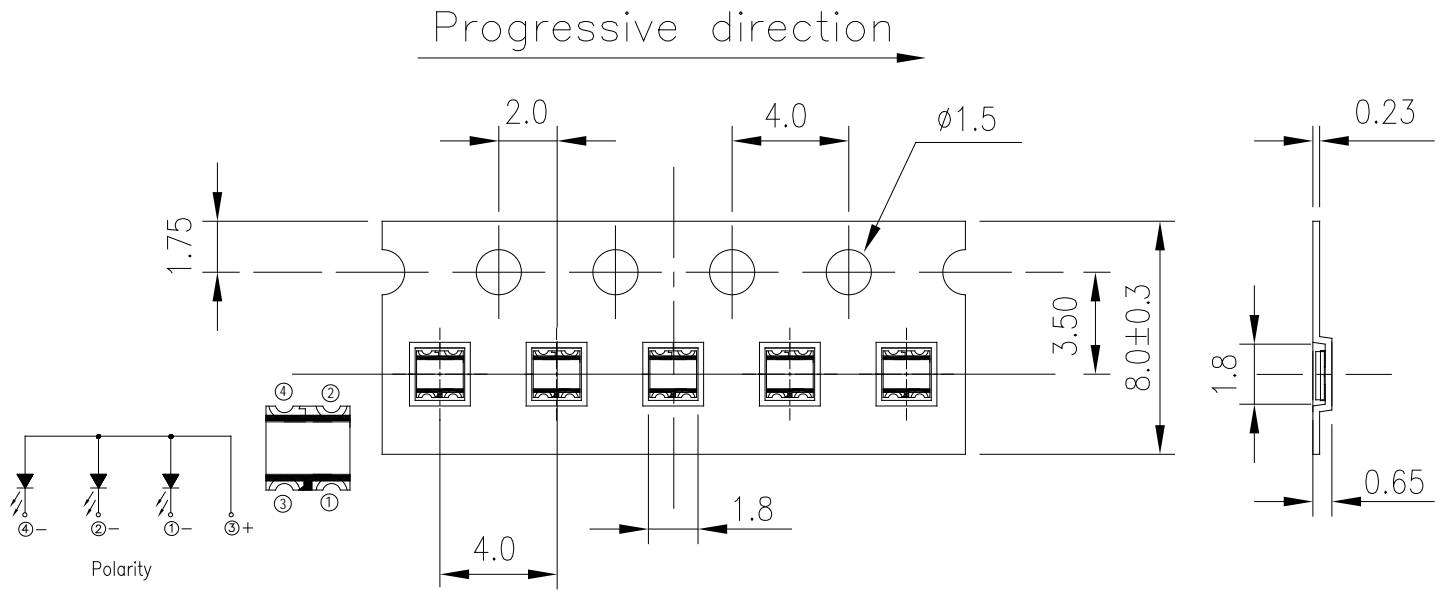## Moisture Resistant Packing Materials

Label Explanation

- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Chromaticity Coordinates & Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number

Reel Dimensions

Note: The tolerances unless mentioned is ±0.1mm ,Unit = mm

www.everlight.com

Carrier Tape Dimensions: Loaded quantity 2000 PCS per reel

Progressive direction

2.0   4.0   ∅1.5

1.75   3.50   8.0±0.3

0.23

1.8

④ ②
③ ①

④ −   ② −   ① −   ③ +

Polarity

4.0   1.8

0.65

Note: The tolerances unless mentioned is ±0.1mm ,Unit = mm

Moisture Resistant Packaging

Label   Aluminum moisture-proof bag   Desiccant   Label
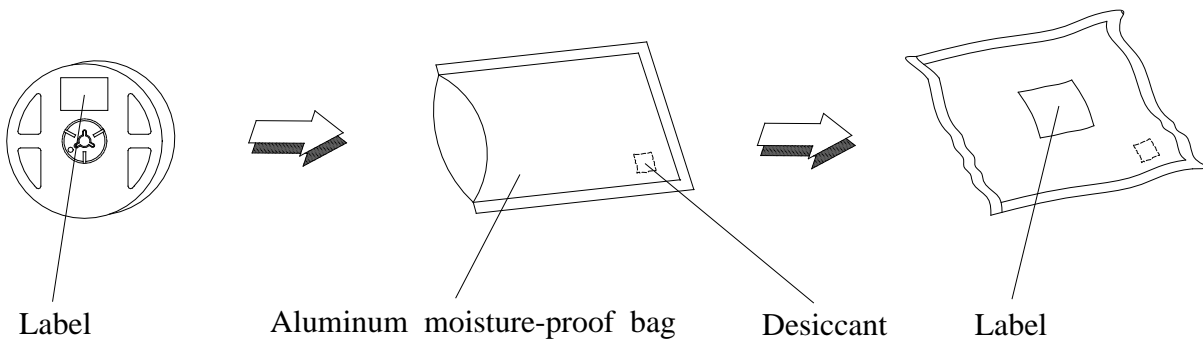
Precautions For Use

1. Over-current-proof
Customer must apply resistors for protection, otherwise slight voltage shift will cause big
current change (Burn out will happen).
2. Storage
  2.1 Do not open moisture proof bag before the products are ready to use.
  2.2 Before opening the package: The LEDs should be kept at 30℃ or less and 90%RH or less.
  2.3 After opening the package: The LED's floor life is 1 year under 30℃ or less and 60% RH or less.
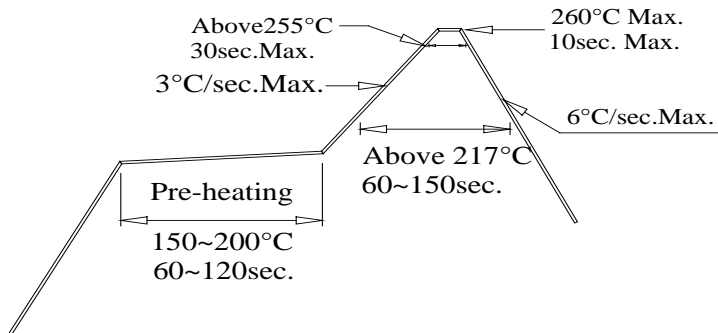If unused LEDs remain, it should be stored in moisture proof packages.
  2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the
storage time, baking treatment should be performed using the following conditions.
Baking treatment : 60±5℃ for 24 hours.
3. Soldering Condition
  3.1 Pb-free solder temperature profile

Above255°C
30sec.Max.

260°C Max.
10sec. Max.

3°C/sec.Max.

6°C/sec.Max.

Above 217°C
60~150sec.

Pre-heating

150~200°C
60~120sec.

  3.2 Reflow soldering should not be done more than two times.
 3.3 When soldering, do not put stress on the LEDs during heating.
  3.4 After soldering, do not warp the circuit board.
4.Soldering Iron
Each terminal is to go to the tip of soldering iron temperature less than 350℃ for 3 seconds within once in less than the
soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because
the damage of the product is often started at the time of the hand solder.

5.Repairing
Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering
iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will
not be damaged by repairing.
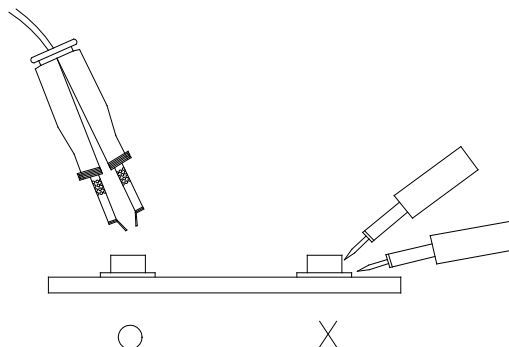
EVERLIGHT

Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.

www.everlight.com